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MacDermid Enthone Electronics Solutions to Exhibit and Present Papers at IPC APEX EXPO 2018

WATERBURY, Conn, USA, January 15, 2018 – Specialty chemicals supplier MacDermid Enthone will reveal new electroplating innovations at IPC APEX EXPO 2018, with papers on any-layer via filling, semi-additive processing, and simultaneous via fill with through-hole plating.

This year, MacDermid Enthone Electronics Solutions will co-exhibit with their sister company Alpha Assembly Solutions. United under the same parent company, the two companies are in a unique position to combine their technology, innovation and service capabilities. As a result, the combined businesses provide the most complete suite of materials' in the entire printed circuit board manufacturing supply chain. At the show, MacDermid Enthone Electronics Solutions will showcase its chemical processes including MacuSpec VF-TH 200, the single step, simultaneously via filling and through hole copper metallization process, Affinity 2.0 the ENIG final finish that meets the latest IPC specifications, as well as the soon-to-be released MacuSpec HT 300 process, a high throw DC acid copper for conformal coating of through holes. In addition, three technology experts from the company will present papers.

Saminda Dharmarathna, Senior Research Chemist, will be presenting, "Advanced Cu Electroplating Process for Any Layer Via Fill Application with Thin Surface Copper" on Tuesday, February 27, 1:30-3:00pm in the PCB Plating Session S01. During that same session, Maria Nikolova, Senior Research Fellow will present "Via Fill and Through Hole Plating Process with Enhanced TH Microdistribution". Fei Peng, Research Project Manager, will be presenting on a "Semi-Additive Process for Variant Polyimide Substrates in Ultra-Fine Flexible Circuits". See her on Thursday, March 1, 9:00-10:00am in the Innovative Concepts in Flexible Circuit Design and Mfg Session S26.

IPC APEX Expo 2018 being held in San Diego, California, February 27-March 1, 2018. For more information on our latest product technologies, visit us at Booth 727.

About MacDermid Enthone Electronics Solutions

MacDermid Enthone Electronics Solutions, a MacDermid Performance Solutions business, researches, formulates and delivers specialty chemistries used in the world's leading electronics. Our products and technical support provide solutions for the most complicated, micro scale circuitry challenges. From wireless devices to automotive and military electronics – in everything you see, and in many things you don't – MacDermid Enthone is there. Visit us at: macdermidenthone.com/electronics.

